EAST Search History

EAST Search History (Prior Art)

Ref#	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S206	1	"6479120".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2010/02/09 16:36

EAST Search History (Interference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	25	william near3 holm.in. and print \$3 with (solder adhesive)	US- PGPUB; USPAT; UPAD	OR	ON	2010/02/15 14:05
L2	0	nils near3 jacobsson.in. and print\$3 with (solder adhesive) not 1	US- PGPUB; USPAT; UPAD	OR	ON	2010/02/15 14:08
L3	8	((((metal\$3 conduct\$3 viscous bond\$3) near4 (material substance paste medium ink slurry liquid solution adhesive glue)) solder\$3) with ((screen stencil squeegee) near3 print\$3) and (detect\$3 recogniz \$3 inspect\$3 evaluat\$3 analyz \$3 calculat\$3 determin\$3) with (((metal\$3 conduct \$3 viscous bond \$3) near4 (material	US- PGPUB; USPAT; UPAD	OR	ON	2010/02/15

solder\$3)).clm. L4	US-			
"5485781" "5786029" "5976269" "6036787" "6626106").PN. OR ("6923117"). URPN.	PGPUB; USPAT	OR	ON	2010/02/15 14:11

L5	29	("4119480" "4636406" "4656048" "5059266" "5110615" "5121329" "5260009" "5280305" "5429682" "5553538" "5594652").PN. OR ("5709905"). URPN.	US- PGPUB; USPAT	OR	ON	2010/02/15 14:13
L6	827	(((metal\$3 conduct \$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder\$3) with (detect\$3 recogniz\$3 inspect \$3 evaluat\$3 analyz\$3) and (((metal\$3 conduct \$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder\$3) with (((screen stencil) near3 print \$3) jet\$4 deposit \$3 apply\$3 dispens \$3 ink\$1jet drop \$4 microdroplet inject\$3) and (((metal\$3 conduct \$3 viscous) near3 (paste medium ink slurry liquid adhesive glue solution)) solder \$3 viscous) near3 (paste medium ink slurry liquid adhesive glue solution)) solder \$1 viscous) solder \$1 viscous) solder \$1 viscous) (restenat\$3 re \$1 viscous) solder \$3	US- PGPUB; USPAT; UPAD	OR	ON	2010/02/15

		add\$1on) near3 (print\$3 jet\$4 solder\$3 apply\$3 dispens\$3)))				
	1	((((metal\$3 conduct\$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder\$3) with (detect\$3 recogniz\$3 inspect \$3 evaluat\$3 analyz\$3) and (((metal\$3 conduct \$3 viscous) near3 (paste medium ink slurry liquid solution adhesive glue)) solder\$3) with (((screen stencil) near3 print \$3) jet\$4 deposit \$3 apply\$3 dispens \$3 ink\$1jet drop \$4 microdroplet inject\$3) and (((metal\$3 conduct \$3 viscous) near3 (paste medium ink slurry liquid adhesive glue solution)) solder \$3) with (re \$1 solder\$3 re \$1 deposit\$3 re \$1 depos	US- PGPUB; USPAT; UPAD	OR	ON	2010/02/15
L8	692	6 and (print\$3 wiring circuit) near3 (board substrate)	US- PGPUB; USPAT; UPAD	OR	ON	2010/02/15 14:23

L9	60	8 and "29"/825- 852.ccls.	US- PGPUB; USPAT; UPAD	OR	ON	2010/02/15 14:23
L10	39	8 and "427"/\$. ccls. not 9	US- PGPUB; USPAT; UPAD	OR	ON	2010/02/15 14:25
L11	11	8 and "101"/\$. ccls. not 9 not 10	US- PGPUB; USPAT; UPAD	OR	ON	2010/02/15 14:27
L12	11	8 and "118"/\$. ccls. not 9 not 10 not 11	US- PGPUB; USPAT; UPAD	OR	ON	2010/02/15 14:28

2/15/10 2:31:10 PM C:\ Documents and Settings\ dnguyen21\ My Documents\ EAST\ Workspaces \ 09901592 Screen_Jet Printg PCB.wsp